



High power cycling capability
Low on-state and switching losses
Designed for traction and industrial applications

Phase Control Thyristor Type T553-800-44

Mean on-state current	I _{TAV}	800 A		
Repetitive peak off-state voltage	V _{DRM}	3800 ÷ 4400 V		
Repetitive peak reverse voltage	V _{RRM}			
Turn-off time	t _q	500, 630, 800 µs		
V _{DRM} , V _{RRM} , V	3800	4000	4200	4400
Voltage code	38	40	42	44
T _j , °C		-60 ÷ 125		

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I _{TAV}	Mean on-state current	A	800 847	T _c =88 °C, Double side cooled T _c =85 °C, Double side cooled 180° half-sine wave; 50 Hz	
I _{TRMS}	RMS on-state current	A	1256	T _c =88 °C, Double side cooled 180° half-sine wave; 50 Hz	
I _{TSM}	Surge on-state current	kA	16.0 18.0	T _j =T _j max T _j =25 °C	180° half-sine wave; t _p =10 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
			17.0 20.0	T _j =T _j max T _j =25 °C	180° half-sine wave; t _p =8.3 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
I ² t	Safety factor	A ² ·10 ³	1200 1600	T _j =T _j max T _j =25 °C	180° half-sine wave; t _p =10 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
			1100 1600	T _j =T _j max T _j =25 °C	180° half-sine wave; t _p =8.3 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
BLOCKING					
V _{DRM} , V _{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	3800÷4400	T _{j min} < T _j <T _j max; 180° half-sine wave; 50 Hz; Gate open	
V _{DSM} , V _{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	3900÷4500	T _{j min} < T _j <T _j max; 180° half-sine wave; single pulse; Gate open	
V _D , V _R	Direct off-state and Direct reverse voltages	V	0.6V _{DRM} 0.6V _{RRM}	T _j =T _j max; Gate open	

TRIGGERING				
I_{FGM}	Peak forward gate current	A	8	$T_j=T_{j \max}$
V_{RGM}	Peak reverse gate voltage	V	5	
P_G	Gate power dissipation	W	4	$T_j=T_{j \max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive ($f=1$ Hz)	A/ μ s	1000	$T_j=T_{j \max}; V_D=0.67V_{DRM}; I_{TM}=2400$ A; Gate pulse: $I_G=2$ A; $t_{GP}=50$ μ s; $di_G/dt \geq 2$ A/ μ s
THERMAL				
T_{stg}	Storage temperature	°C	-60÷50	
T_j	Operating junction temperature	°C	-60÷125	
MECHANICAL				
F	Mounting force	kN	24.0÷28.0	
a	Acceleration	m/s ²	50	Device clamped

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions
ON-STATE				
V_{TM}	Peak on-state voltage, max	V	2.60	$T_j=25$ °C; $I_{TM}=2512$ A
$V_{T(TO)}$	On-state threshold voltage, max	V	1.144	$T_j=T_{j \max};$
r_T	On-state slope resistance, max	$m\Omega$	0.713	$0.5 \pi I_{TAV} < I_T < 1.5 \pi I_{TAV}$
I_L	Latching current, max	mA	1500	$T_j=25$ °C; $V_D=12$ V; Gate pulse: $I_G=2$ A; $t_{GP}=50$ μ s; $di_G/dt \geq 1$ A/ μ s
I_H	Holding current, max	mA	300	$T_j=25$ °C; $V_D=12$ V; Gate open
BLOCKING				
I_{DRM}, I_{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	150	$T_j=T_{j \max};$ $V_D=V_{DRM}; V_R=V_{RRM}$
$(dv_D/dt)_{crit}$	Critical rate of rise of off-state voltage ¹⁾ , min	V/ μ s	200, 320, 500, 1000, 1600, 2000, 2500	$T_j=T_{j \max};$ $V_D=0.67V_{DRM}$; Gate open
TRIGGERING				
V_{GT}	Gate trigger direct voltage, max	V	3.00 2.50 1.50	$T_j=T_{j \min}$ $T_j=25$ °C $T_j=T_{j \max}$
I_{GT}	Gate trigger direct current, max	mA	400 250 150	$T_j=T_{j \min}$ $T_j=25$ °C $T_j=T_{j \max}$
V_{GD}	Gate non-trigger direct voltage, min	V	0.35	$T_j=T_{j \max};$
I_{GD}	Gate non-trigger direct current, min	mA	40.00	$V_D=0.67V_{DRM};$ Direct gate current
SWITCHING				
t_{gd}	Delay time, max	μ s	2.75	$T_j=25$ °C; $V_D=1500$ V; $I_{TM}=I_{TAV};$ $di/dt=200$ A/ μ s;
t_{gt}	Turn-on time, max	μ s	16.0	Gate pulse: $I_G=2$ A; $V_G=20$ V; $t_{GP}=50$ μ s; $di_G/dt=2$ A/ μ s
t_q	Turn-off time ²⁾ , max	μ s	500, 630, 800	$dv_D/dt=50$ V/ μ s; $T_j=T_{j \max}$; $I_{TM}=I_{TAV};$ $di_R/dt=-5$ A/ μ s; $V_R=100$ V; $V_D=0.67V_{DRM}$
Q_{rr}	Total recovered charge, max	μ C	3300	$T_j=T_{j \max}$; $I_{TM}=800$ A;
t_{rr}	Reverse recovery time, max	μ s	55	$di_R/dt=-5$ A/ μ s;
I_{rrM}	Peak reverse recovery current, max	A	120	$V_R=100$ V;

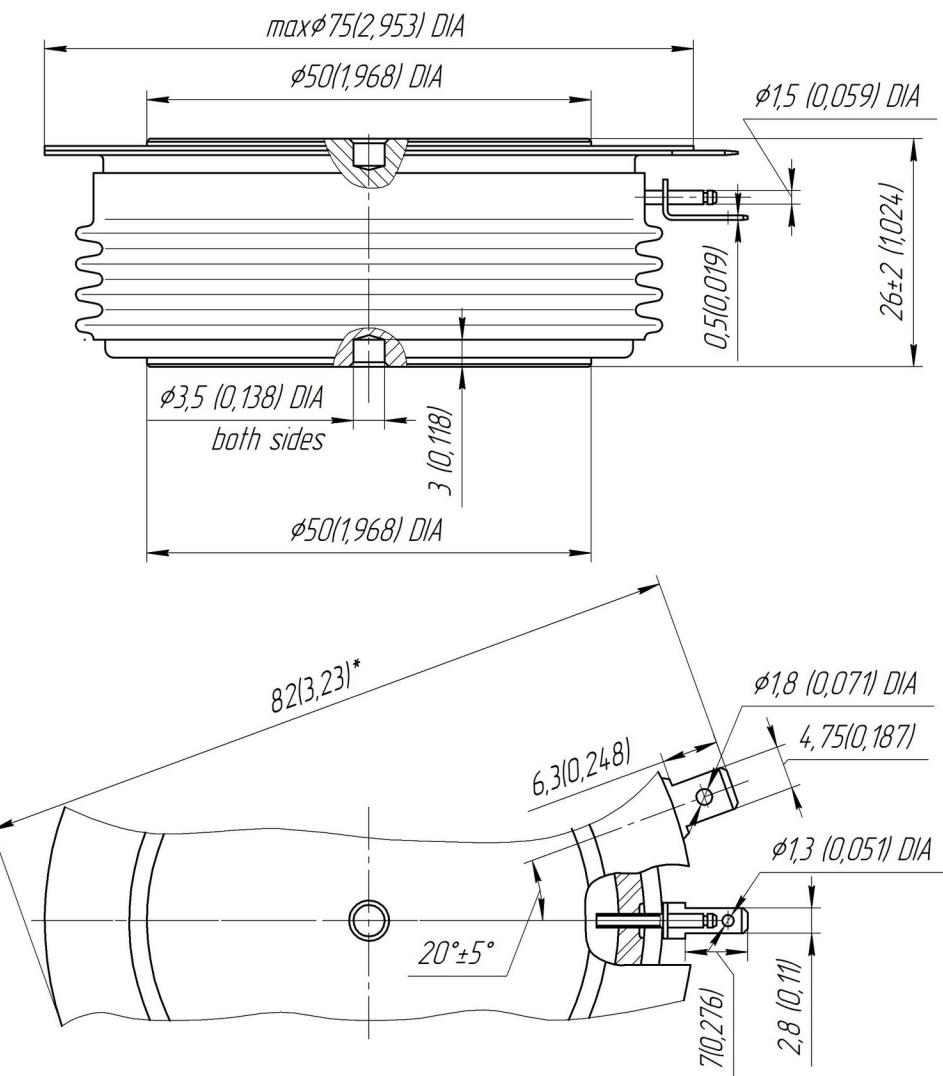
THERMAL						
R_{thjc}	Thermal resistance, junction to case, max			0.0180	Direct current	Double side cooled
R_{thjc-A}				0.0396		Anode side cooled
R_{thjc-K}				0.0324		Cathode side cooled
R_{thck}	Thermal resistance, case to heatsink, max		$^{\circ}\text{C}/\text{W}$	0.0040	Direct current	

MECHANICAL						
W	Weight, max		g	510		
D_s	Surface creepage distance		mm (inch)	30.38 (1.196)		
D_a	Air strike distance		mm (inch)	18.05 (0.710)		

PART NUMBERING GUIDE							NOTES																																		
<table border="1"> <tr> <td>T</td><td>553</td><td>800</td><td>44</td><td>A2</td><td>B2</td><td>N</td><td colspan="7"></td></tr> <tr> <td>1</td><td>2</td><td>3</td><td>4</td><td>5</td><td>6</td><td>7</td><td colspan="7"></td></tr> </table>							T	553	800	44	A2	B2	N								1	2	3	4	5	6	7														
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1. Phase Control Thyristor							1) Critical rate of rise of off-state voltage																																		
2. Design version							<table border="1"> <tr> <td>Symbol of Group (dv_o/dt)_{crit}, V/μs</td><td>P2</td><td>K2</td><td>E2</td><td>A2</td><td>T1</td><td>P1</td><td>M1</td></tr> <tr> <td>200</td><td>320</td><td>500</td><td>1000</td><td>1600</td><td>2000</td><td>2500</td><td></td></tr> </table>								Symbol of Group (dv_o/dt) _{crit} , V/ μs	P2	K2	E2	A2	T1	P1	M1	200	320	500	1000	1600	2000	2500												
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4. Voltage code							<table border="1"> <tr> <td>Symbol of Group t_{tr}, μs</td><td>E2</td><td>C2</td><td>B2</td><td></td><td></td><td></td><td></td></tr> <tr> <td>500</td><td>630</td><td>800</td><td></td><td></td><td></td><td></td><td></td></tr> </table>									Symbol of Group t_{tr} , μs	E2	C2	B2					500	630	800															
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7. Ambient conditions: N – normal; T – tropical																																									

OVERALL DIMENSIONS

Package type: T.D5



All dimensions in millimeters (inches)

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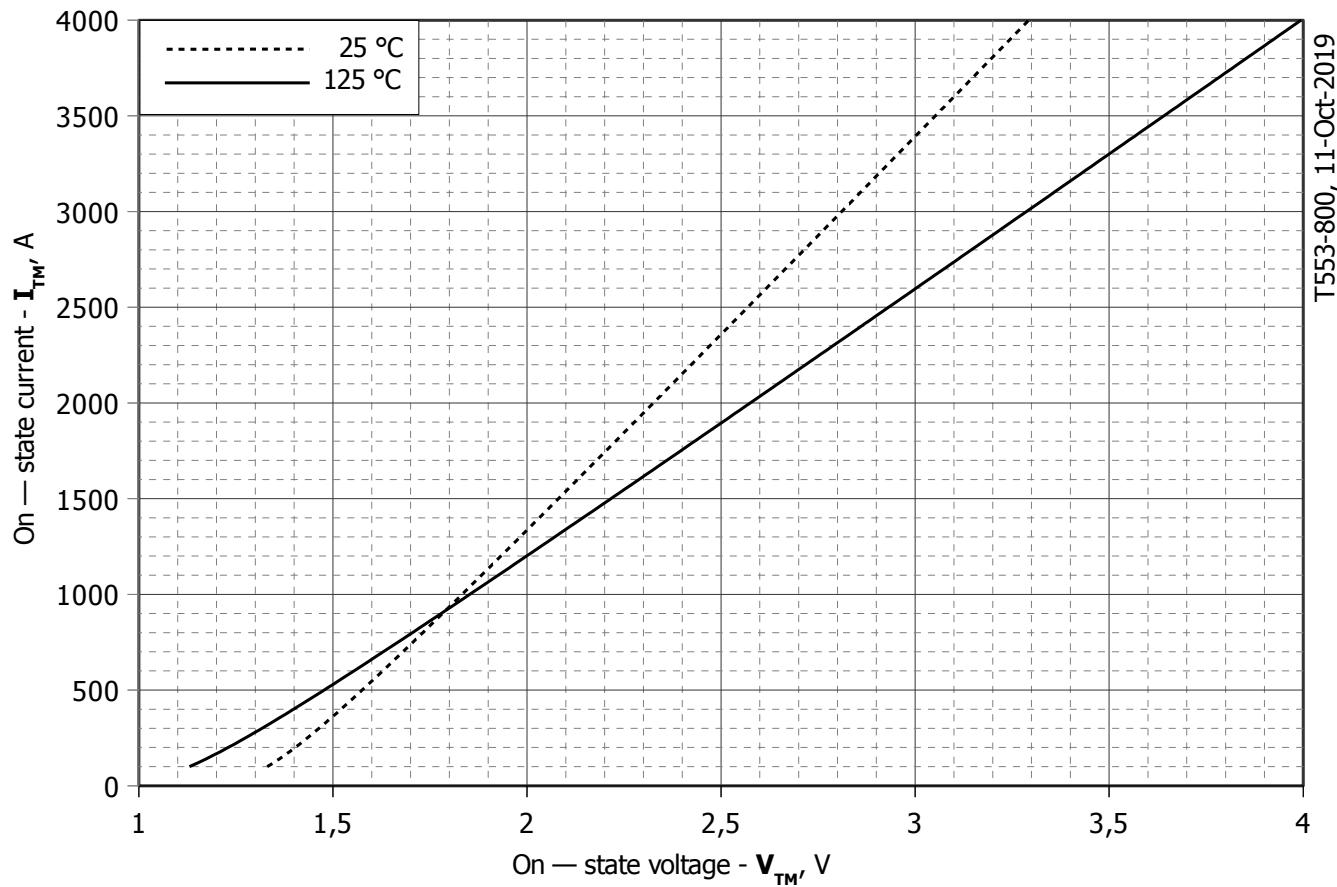


Fig 1 – On-state characteristics of Limit device

Analytical function for On-state characteristic:

$$V_T = A + B \cdot i_T + C \cdot \ln(i_T + 1) + D \cdot \sqrt{i_T}$$

	Coefficients for max curves	
	$T_j = 25^\circ\text{C}$	$T_j = T_{j,\max}$
A	1.09600000	0.84157000
B	0.00048225	0.00070287
C	0.04364400	0.04978800
D	-0.00148650	-0.00113010

On-state characteristic model (see Fig. 1)

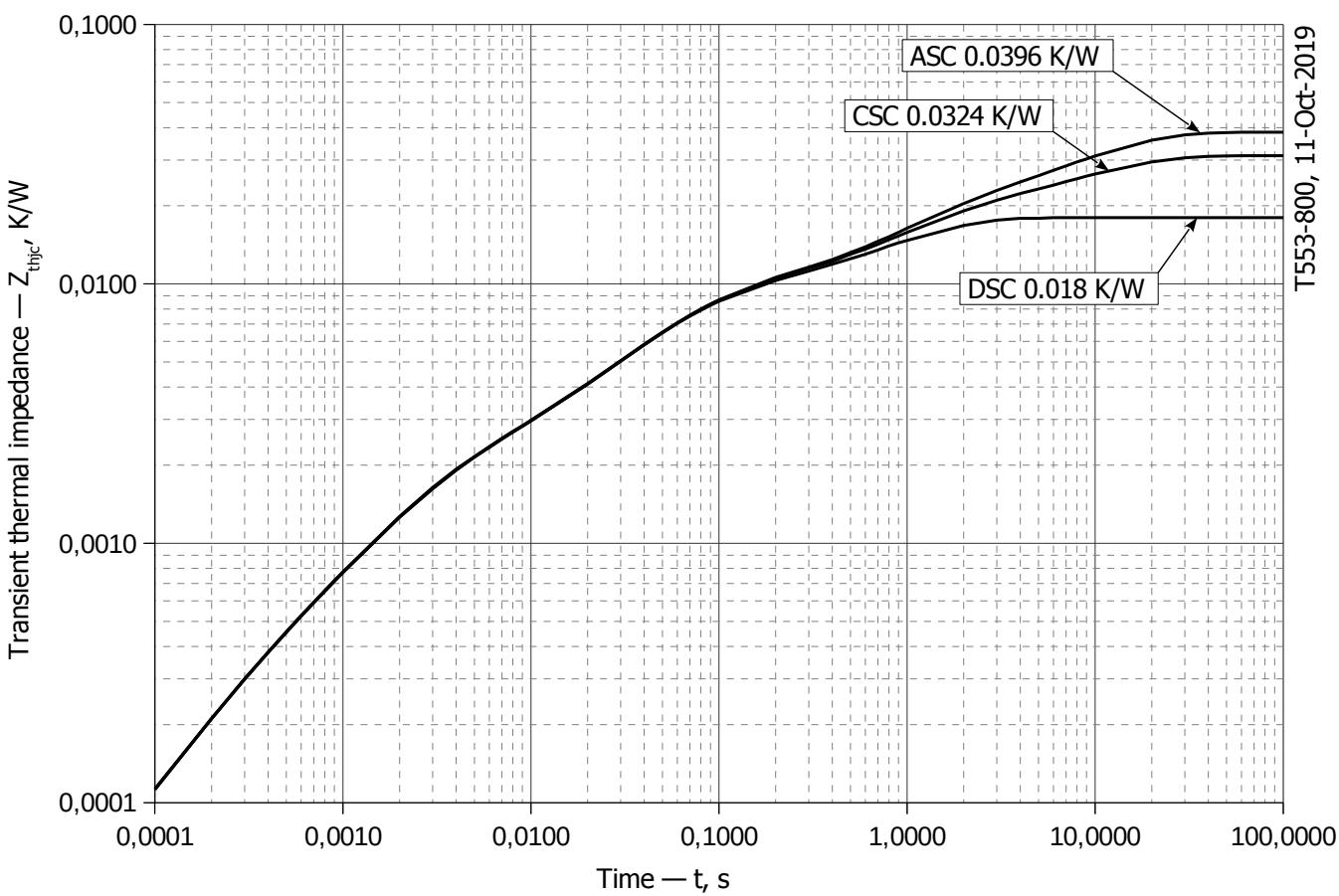


Fig 2 – Transient thermal impedance Z_{thjc} vs. time t

Analytical function for Transient thermal impedance junction to case Z_{thjc} for DC:

$$Z_{thjc} = \sum_{i=1}^n R_i \left(1 - e^{-\frac{t}{\tau_i}} \right)$$

Where $i = 1$ to n , n is the number of terms in the series.

t = Duration of heating pulse in seconds.

Z_{thjc} = Thermal resistance at time t .

R_i = Amplitude of p_{th} term.

τ_i = Time constant of r_{th} term.

DC Double side cooled

i	1	2	3	4	5	6
R_i , K/W	0.009241	0.006037	0.001231	0.001054	0.0003396	0.00009575
τ_i , s	0.9673	0.04967	0.002733	0.07734	0.001638	0.0002248

DC Anode side cooled

i	1	2	3	4	5	6
R_i , K/W	0.01318	0.009281	0.006055	0.001018	0.001535	0.0001182
τ_i , s	9.745	1.028	0.05591	0.03732	0.002468	0.0002687

DC Cathode side cooled

i	1	2	3	4	5	6
R_i , K/W	0.02041	0.009325	0.006949	0.0001252	0.001516	0.0001119
τ_i , s	9.752	1.065	0.05344	0.01407	0.002421	0.0002554

Transient thermal impedance junction to case Z_{thjc} model (see Fig. 2)

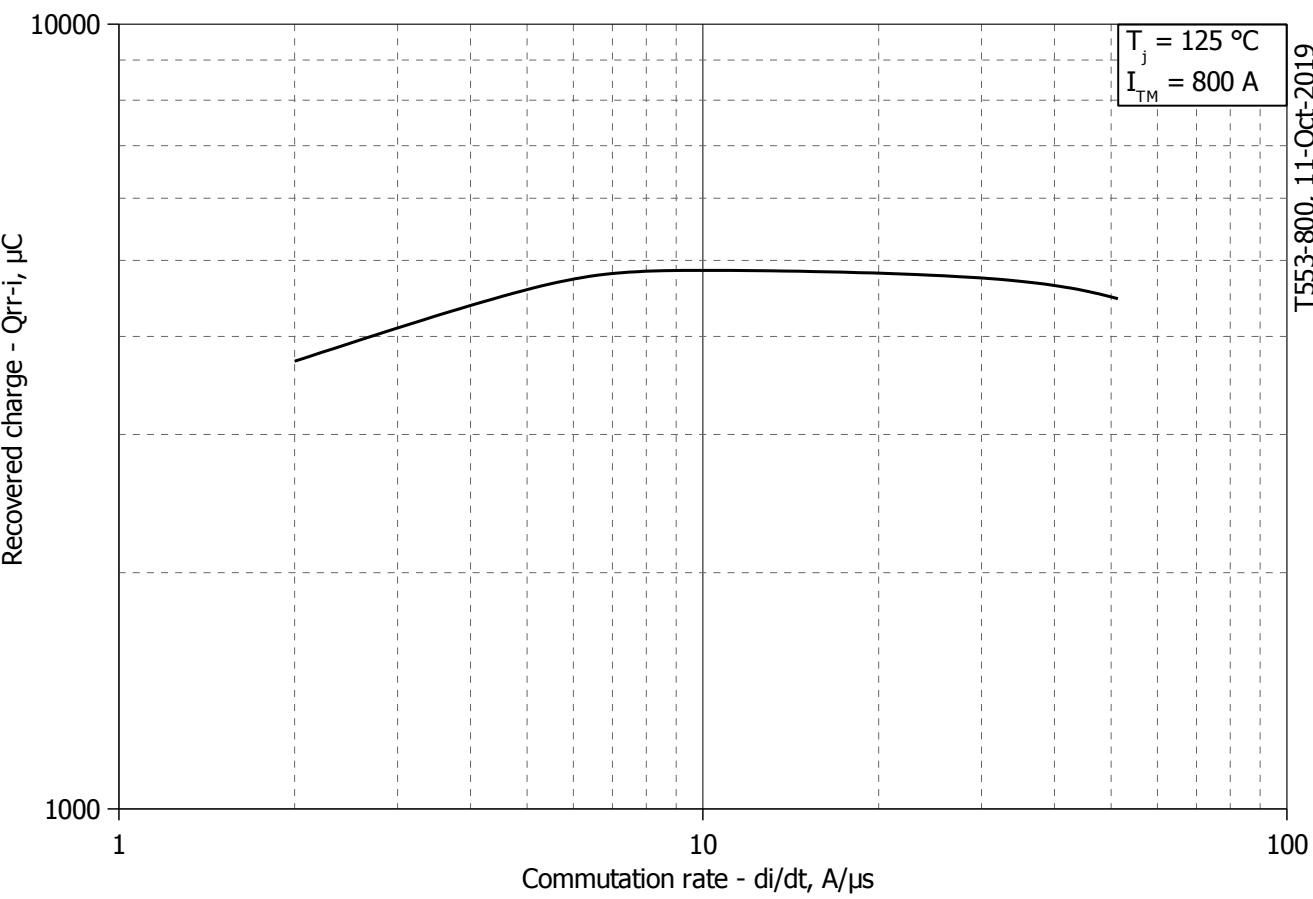


Fig 3 – Maximum recovered charge Q_{rr-i} (integral) vs. commutation rate di_R/dt

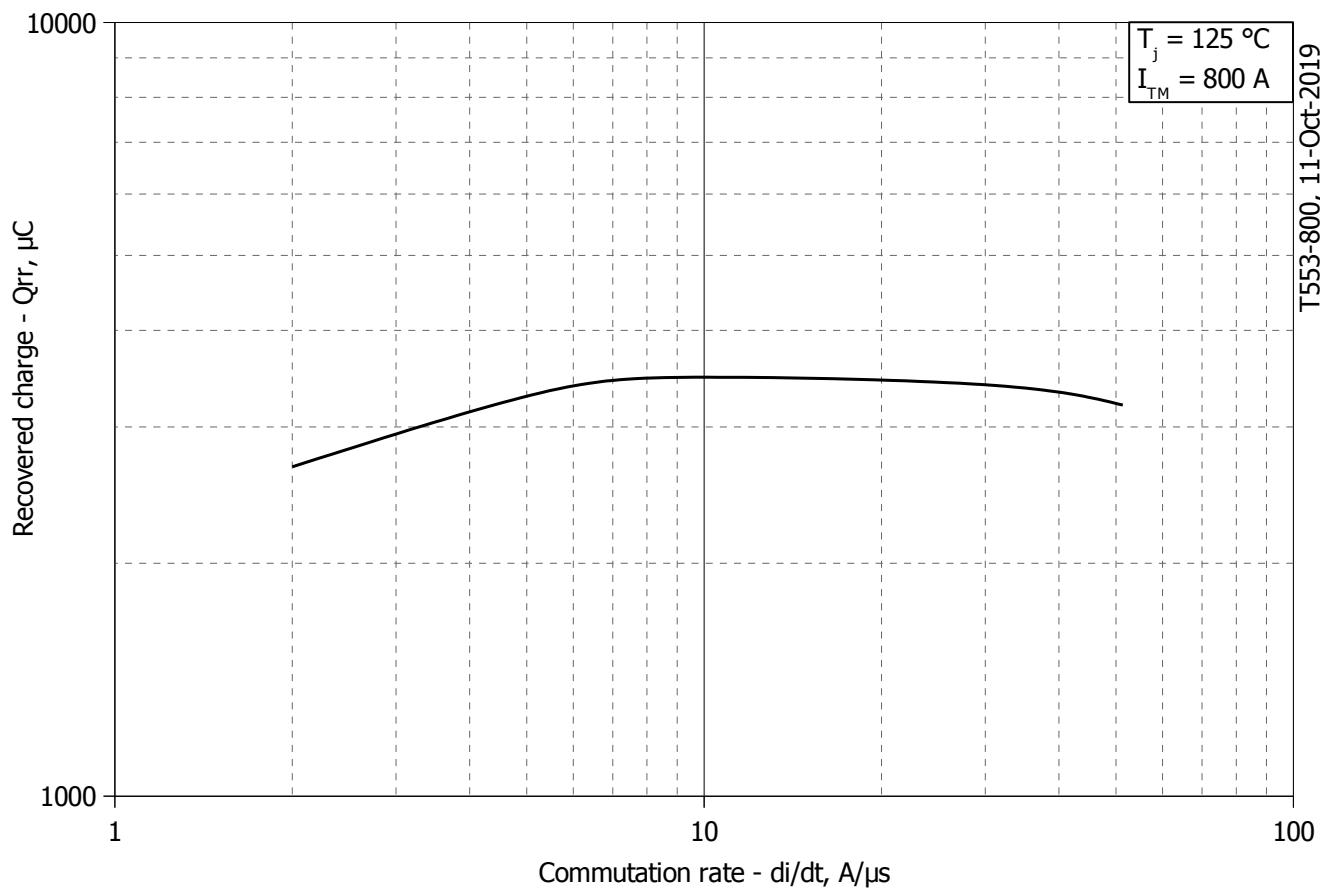
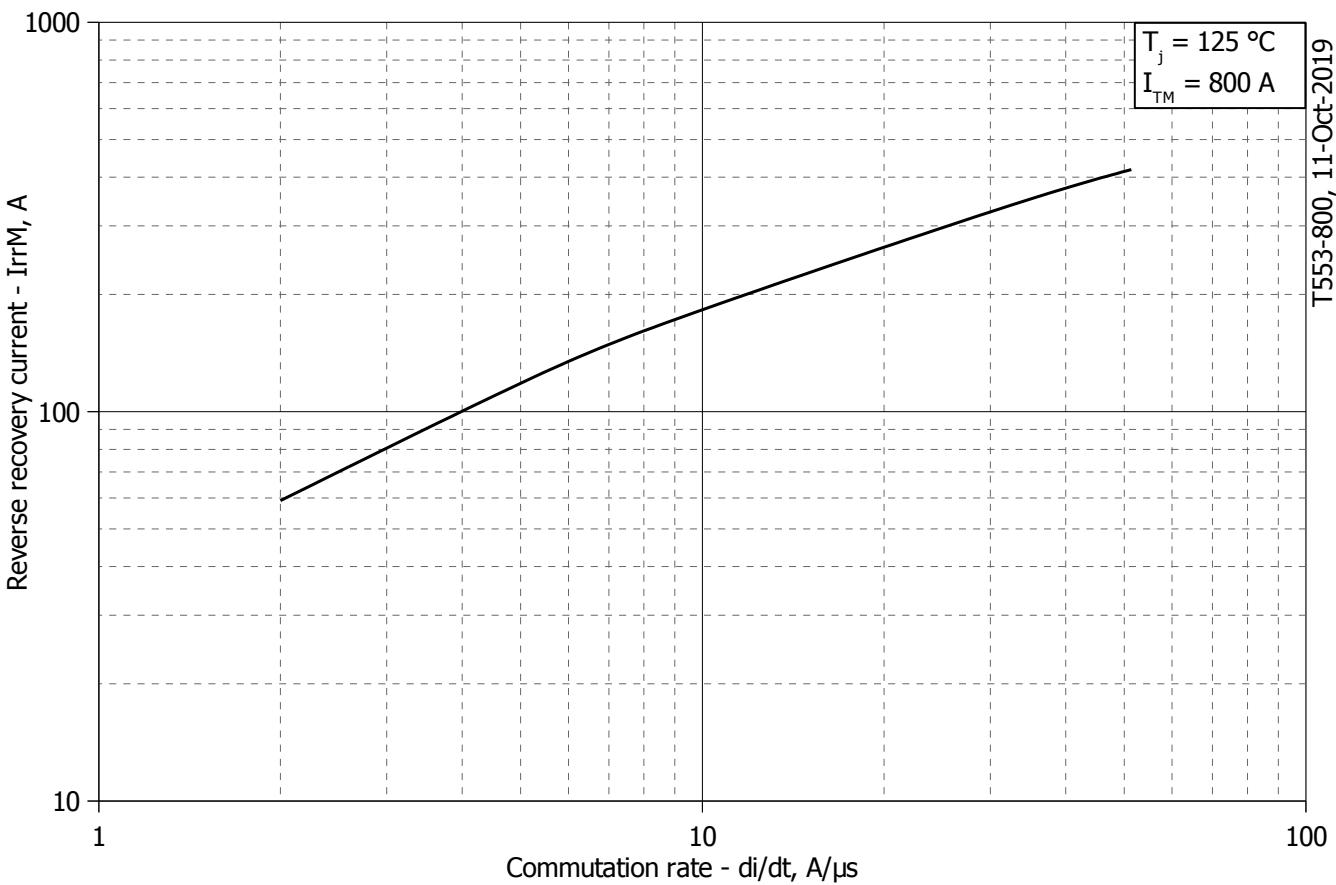
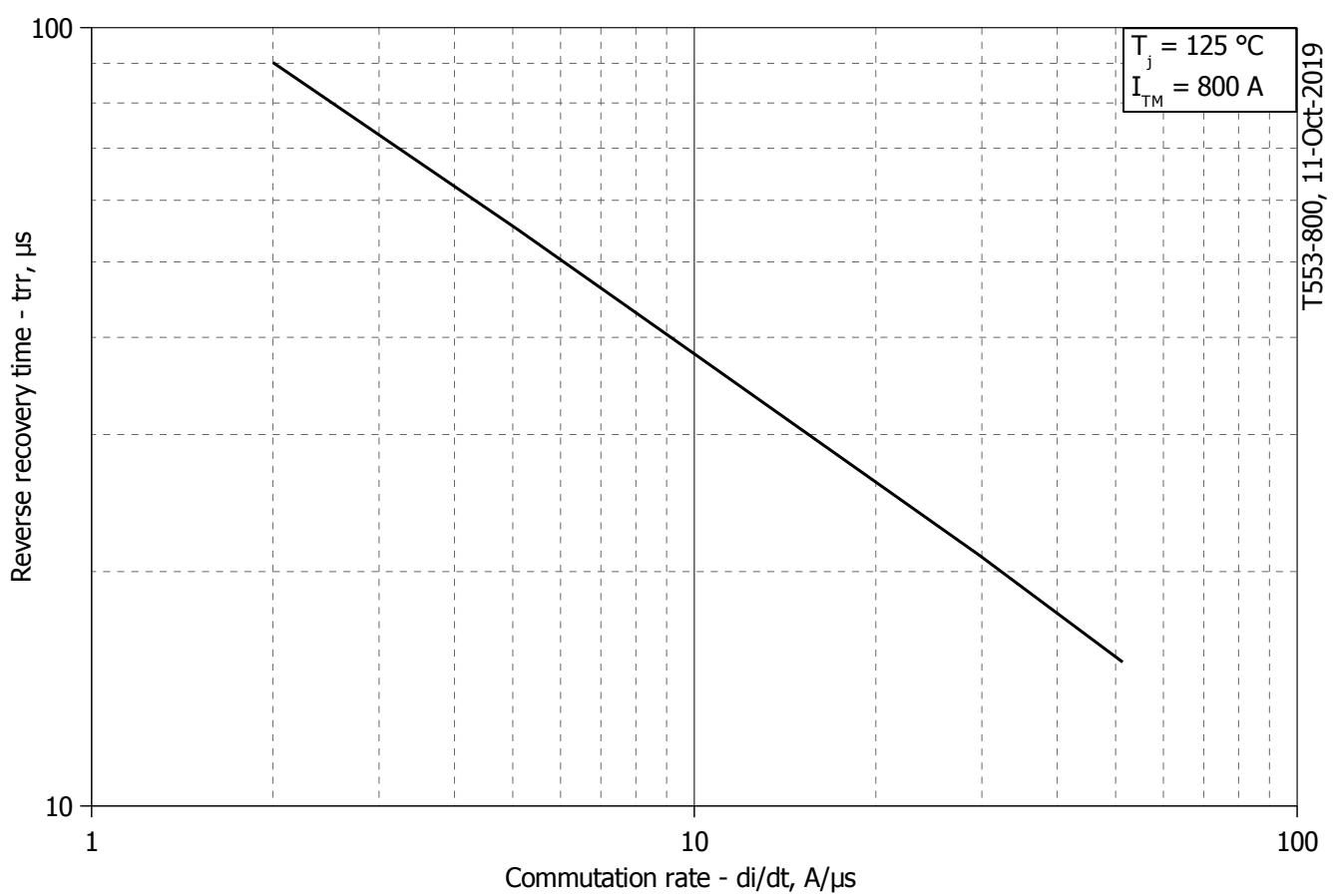


Fig 4 – Maximum recovered charge Q_{rr} vs. commutation rate di_R/dt (25% chord)



T553-800, 11-Oct-2019



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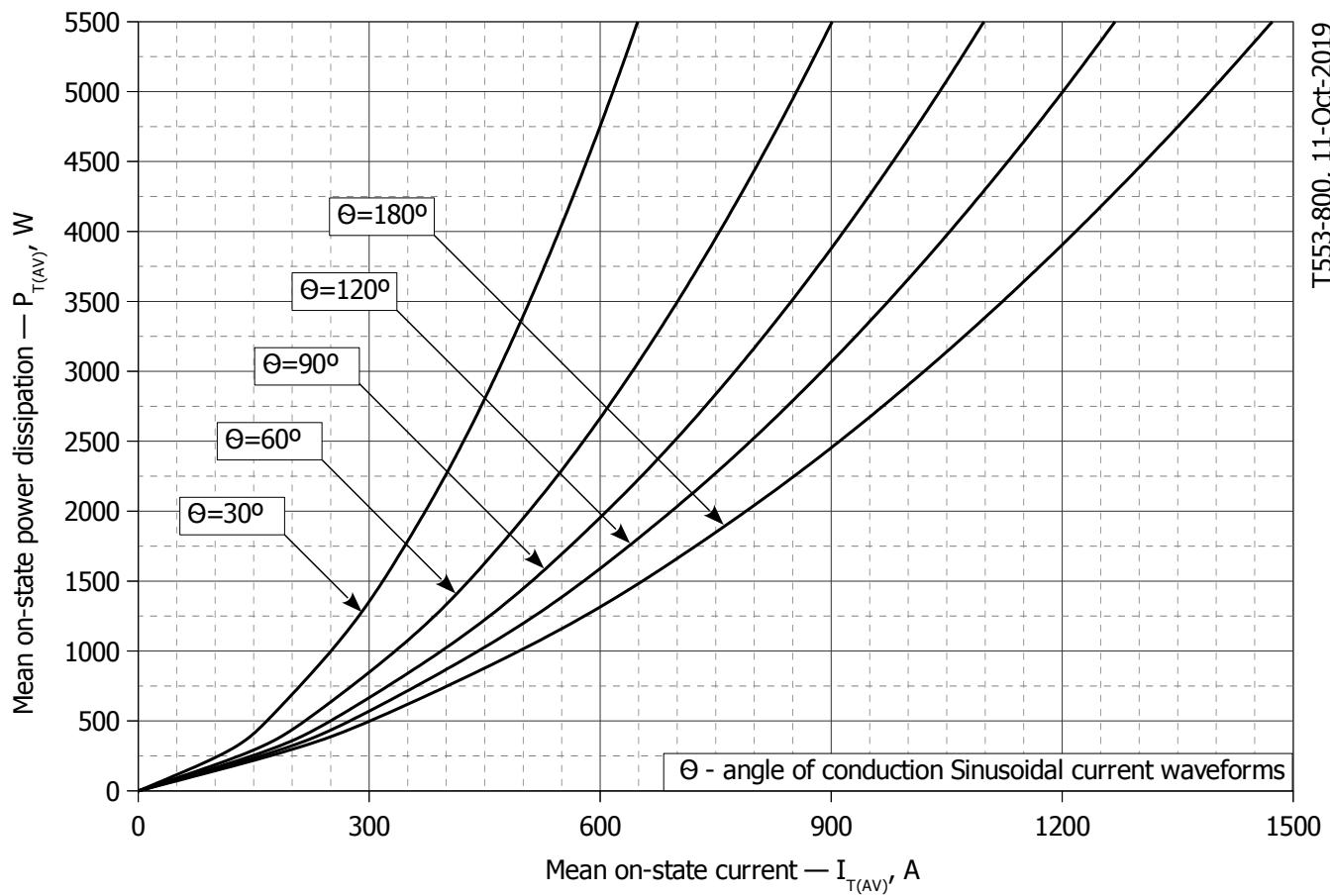


Fig. 7 - Mean on-state power dissipation P_{TAV} vs. mean on-state current I_{TAV} for sinusoidal current waveforms at different conduction angles (f=50Hz, DSC)

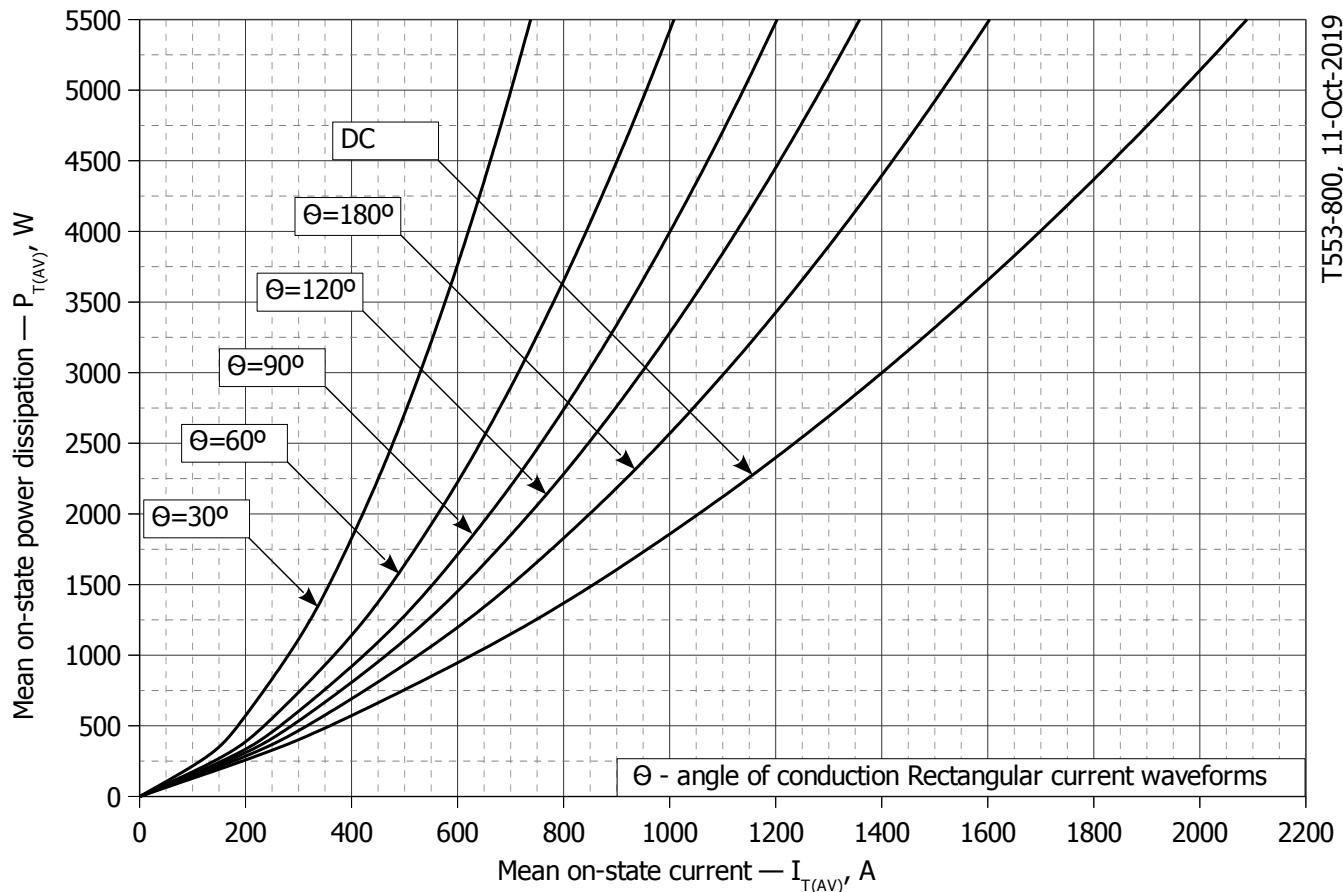


Fig. 8 – Mean on-state power dissipation P_{TAV} vs. mean on-state current I_{TAV} for rectangular current waveforms at different conduction angles and for DC (f=50Hz, DSC)

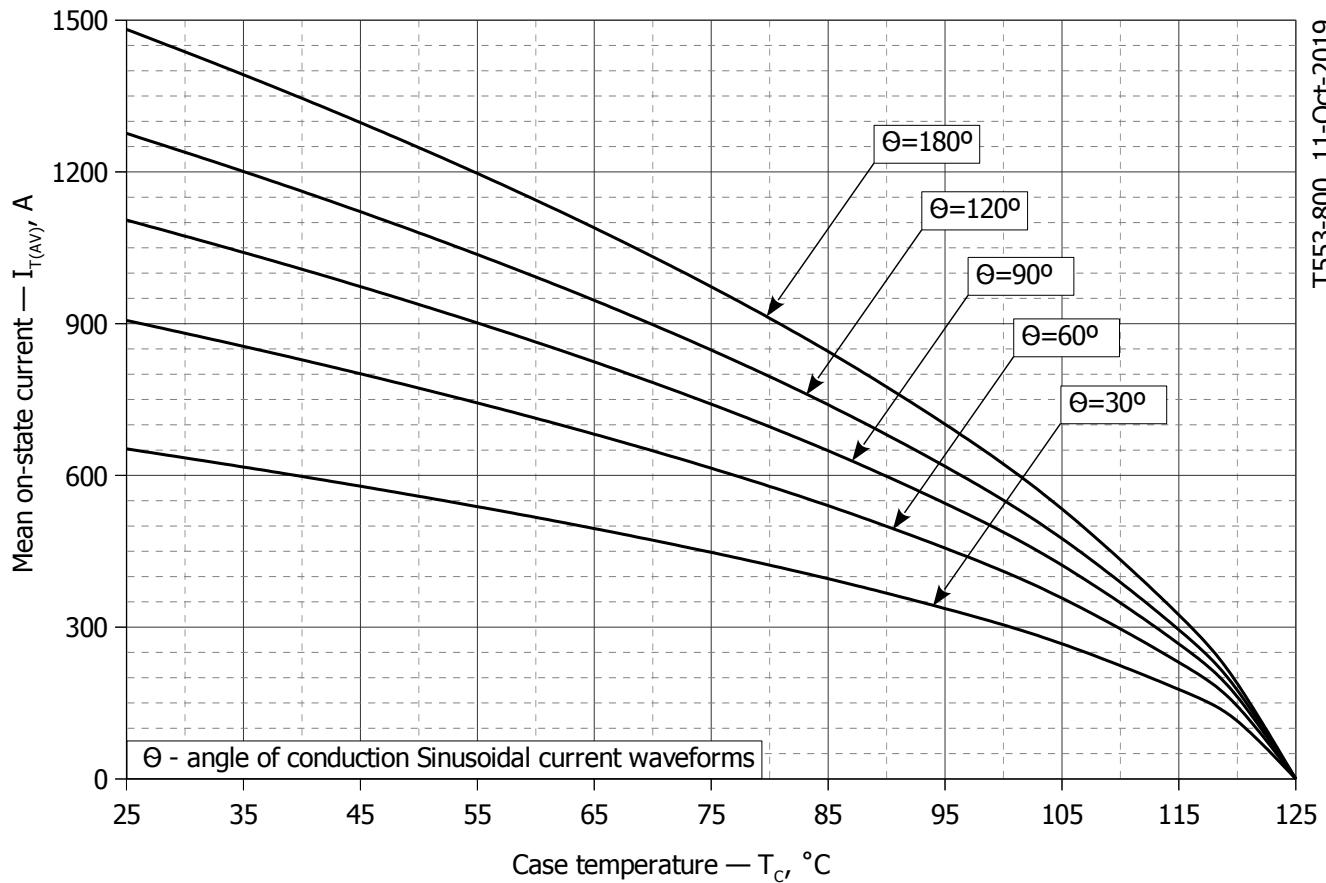


Fig. 9 – Mean on-state current I_{TAV} vs. case temperature T_c for sinusoidal current waveforms at different conduction angles (f=50Hz, DSC)

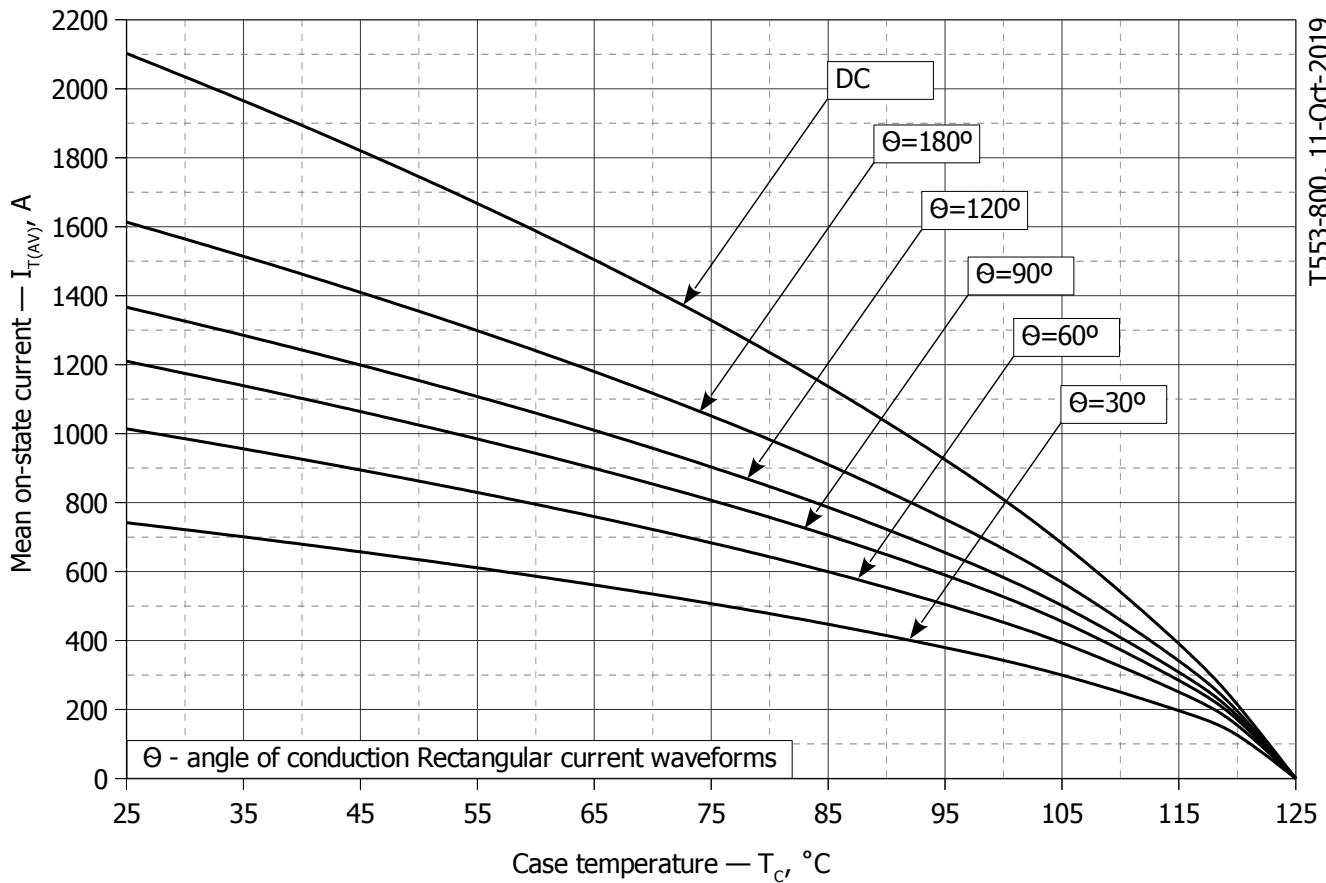


Fig. 10 - Mean on-state current I_{TAV} vs. case temperature T_c for rectangular current waveforms at different conduction angles and for DC (f=50Hz, DSC)

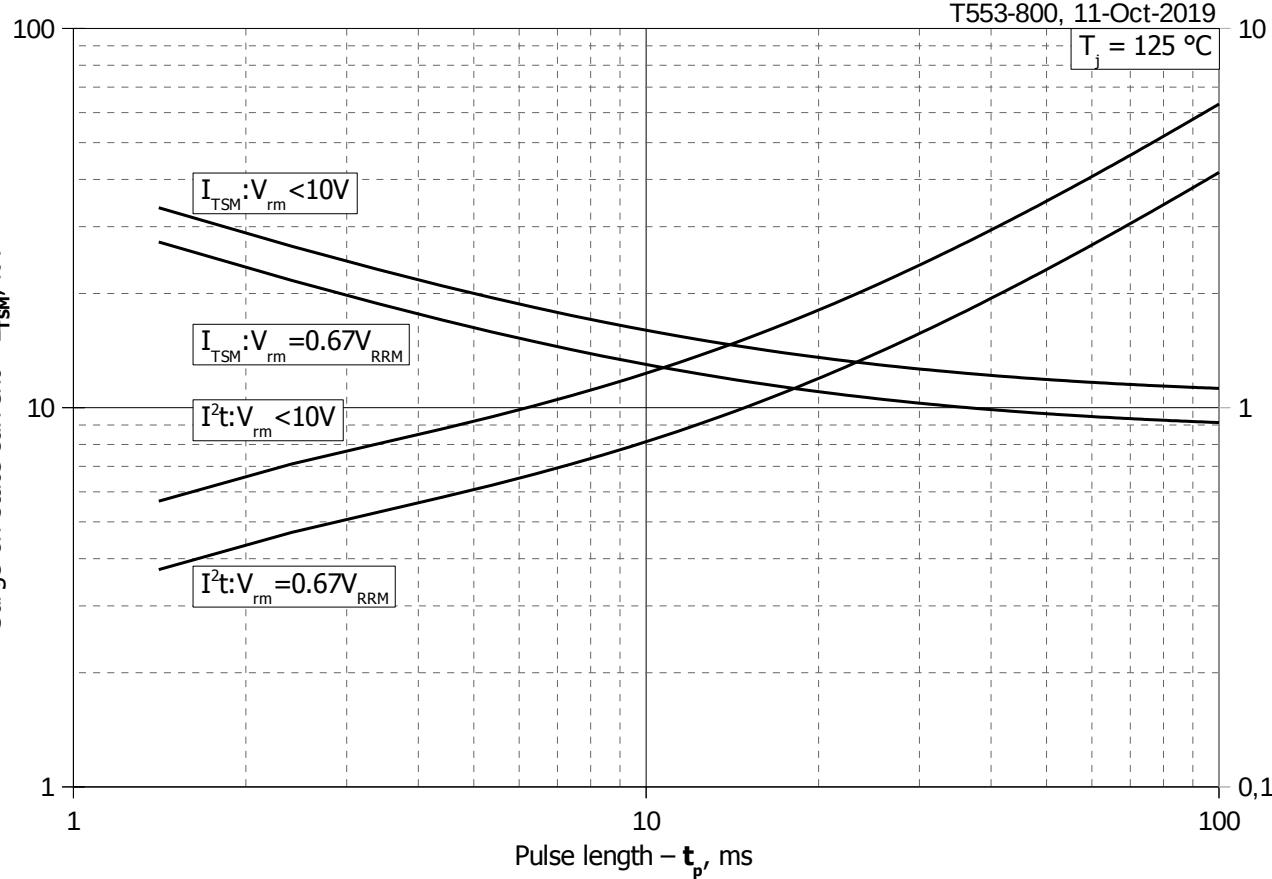


Fig. 11 – Maximum surge on-state current I_{TSM} and safety factor I^2t vs. pulse length t_p

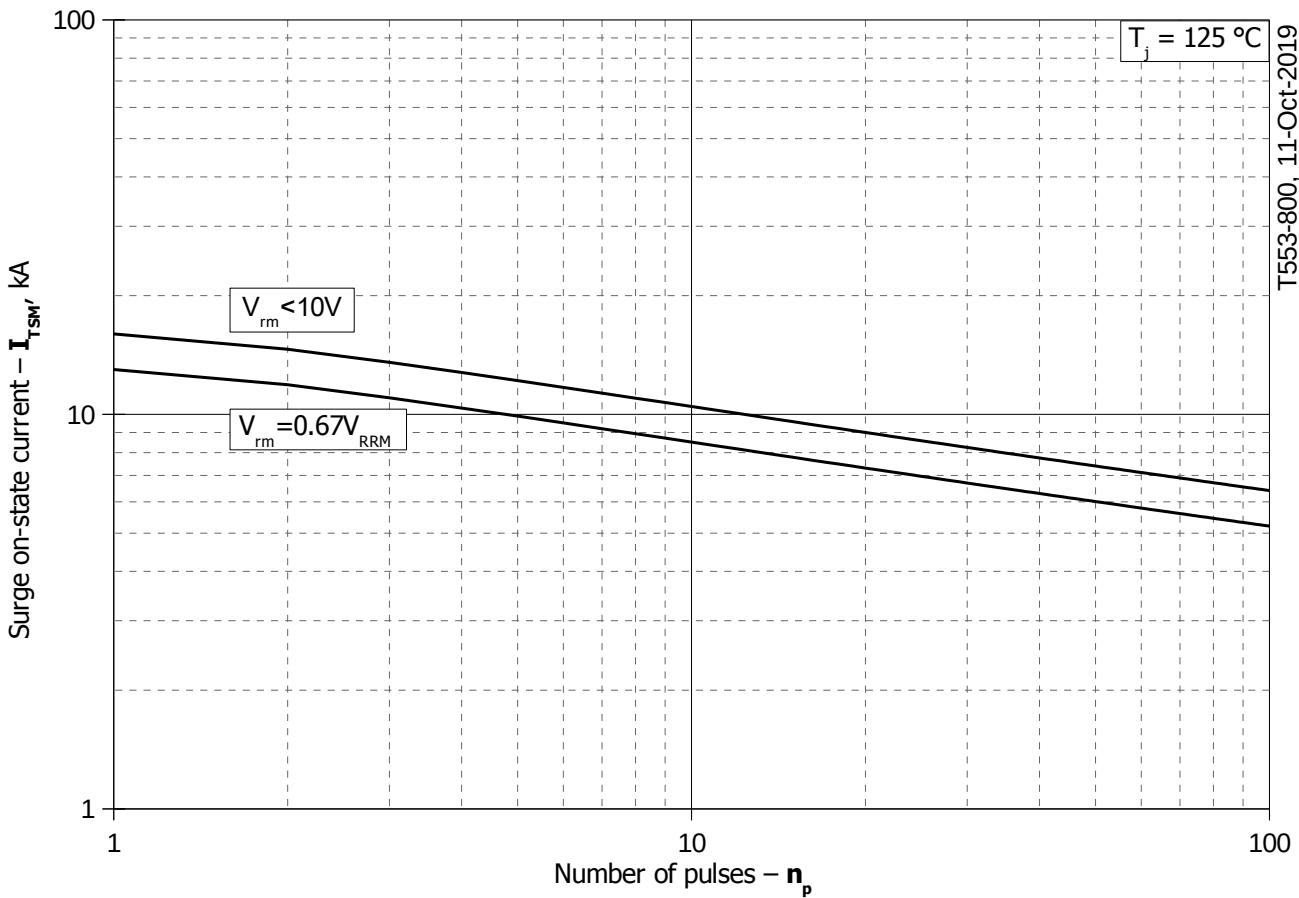


Fig. 12 - Maximum surge on-state current I_{TSM} vs. number of pulses n_p